

# SP8782A & B

# 1GHz ÷ 16/17, ÷32/33 Multi-Modulus Divider

Issue 2.4

loop delay effects

Multi-Modulus division

# DS3651

June 1999

Odering Information SP8782 A DG SP8782 B MP DES9208901/AC/DGAZ(SMD)

# Description

**Features** 

The SP8782 is a multi-modulus divider which divides by 16/ 17 when the Ratio Select input is low and by 32/33 when theRatio Select input is high. When high, the modulus Control input selects the lower division ratio (16 or 32) and the higher ratio (17 or 33) when it is low.

Advanced Resynchronisation techniques to negate

Available as DESC SMD 5962-9208901MPA

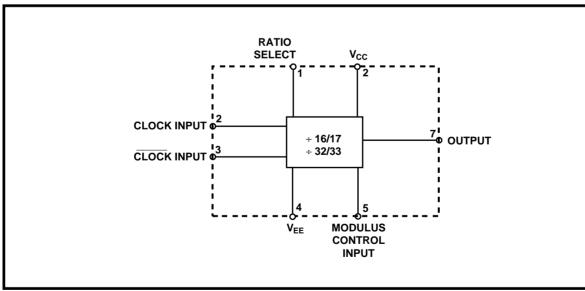
CMOS compataible output capability

The device uses resynchronisation techniques to reduce the effects of propagation delays in frequency synthesis.

The SP8782A (ceramic DIL package) is characterised over the full military temperature range of -55°C to +125°C, the SP8782B (miniature plastic DIL package) over the industrial range of -40°C to+85°C.

## **Absolute Maximum Ratings**

Supply Voltage	6V
Clock input level	2.5V p-p
Junction temperature	+175°C
Storage temperature range:	
SP8782A	-55°C to +150°C
SP8782B	-55°C to +125°C



### Figure 1 Functional Diagram

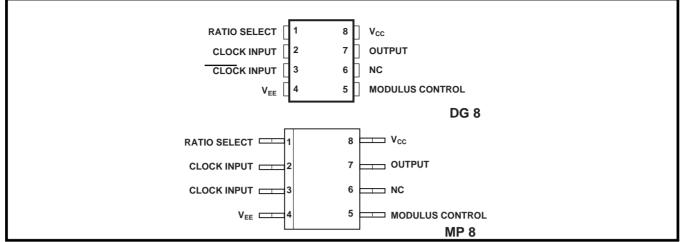


Figure 2 Typical Pin Connections

# **Electrical Characteristics**

Unless otherwise stated, the Electrical Characteristics are guaranteed over the specified supply, frequency and temperature range.

Supply Voltage,  $V_{cc} = +4V$  to +5.5V,  $V_{EE} = 0V$ 

Temperature T<sub>amb</sub>= -55°C to +125°C, (SP8782A), -40°C to +85° C (SP8782B)

Characteristic	Pin	Value			Conditions
		Min	Max	Units	
Maximum frequency	2, 3	1		GHz	Input = 200-1200mVp-p
(sinewave input)					
Minimum frequency	2, 3		50	MHz	Input = 400-1200mVp-p
Min Slew rate for low frequency operation	2, 3		100	V/µs	
Power Supply current, I <sub>cc</sub>	8		60	mA	Output unloaded, $V_{cc}$ =5.5V
Output low voltage	7	0	1.7	V	
Output high voltage	7	V <sub>cc</sub> -1.4	V <sub>cc</sub>	V	
Modulus control input high voltage	5	0.7V <sub>cc</sub>	V <sub>cc</sub>	V	At driver end of $3k\Omega$ resistor
Modulus control input low voltage	5	0	$0.3V_{cc}$	V	At driver end of $3k\Omega$ resistor
Modulus control input high current	5	0.6	1.2	mA	Via 3k $\Omega$ resistor to V <sub>cc</sub>
Modulus control input low current	5	-0.6	-1.2	mA	Via 3k $\Omega$ resistor to V <sub>cc</sub>
Ratio select input high voltage	1	0.6V <sub>cc</sub>	V <sub>cc</sub>	V	
Ratio selected input low voltage	1	0	$0.4V_{cc}$	V	
Ratio select input current	1	-10	10	μA	
Clock to output propagation Delay	2,3,7		3	ns	
Set-up time, t	5,7	3		ns	See note 1 and Fig. 3a
Release time,t,	5,7	3		ns	See note 2 and Fig. 3b

Notes: 1. The set-up time  $t_s$  is defined as the minimum time that can elapse between L $\rightarrow$ H transition of the

modulus control input and the next L→H output transition to ensure that the ÷ 16 (32) mode is obtained.
The release time t<sub>r</sub> is defined as the minimum time that can elapse between H→L transition of the modulus control input and the next L→H output transition to ensure that the ÷ 17 (33) mode is obtained.

Modulus control	Ratio select input			
input	0	1		
0	÷17	÷33		
1	÷16	÷32		

Table 1	Truth	table	for	control	inputs
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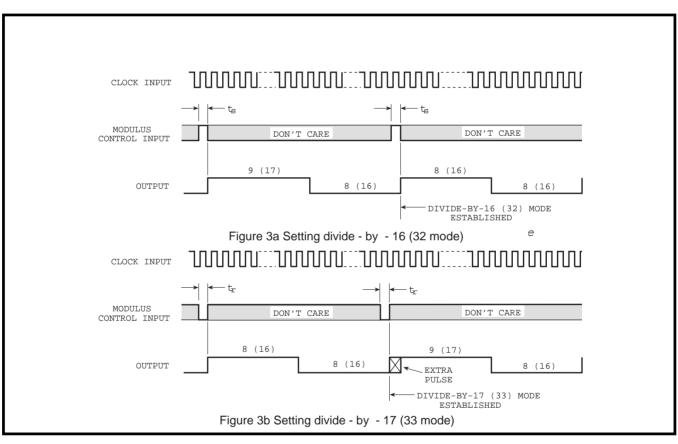


Figure 3 Timing diagrams

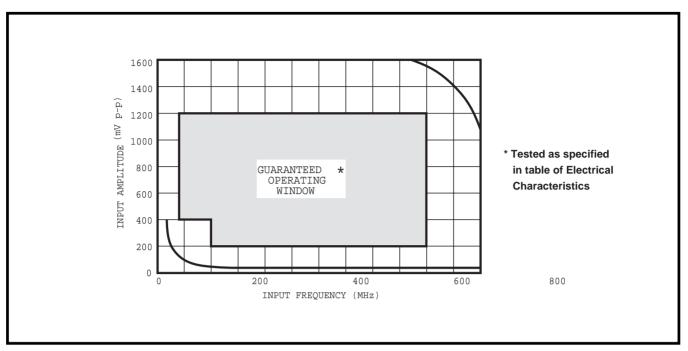


Figure 4 Typical input characteristics

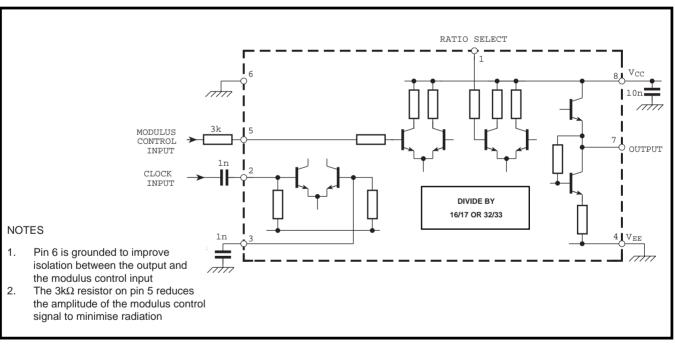


Figure 5 Typical application showing interfacing

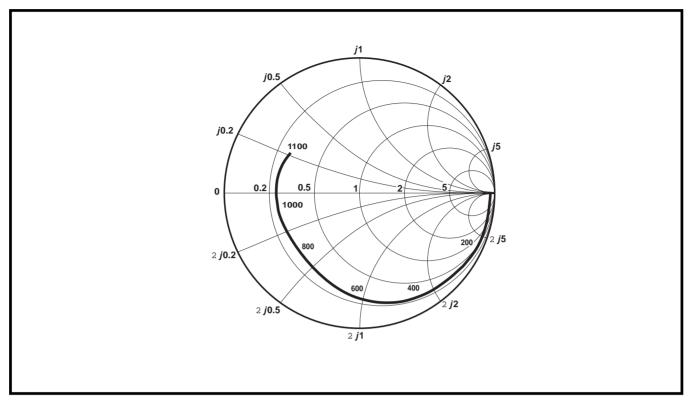
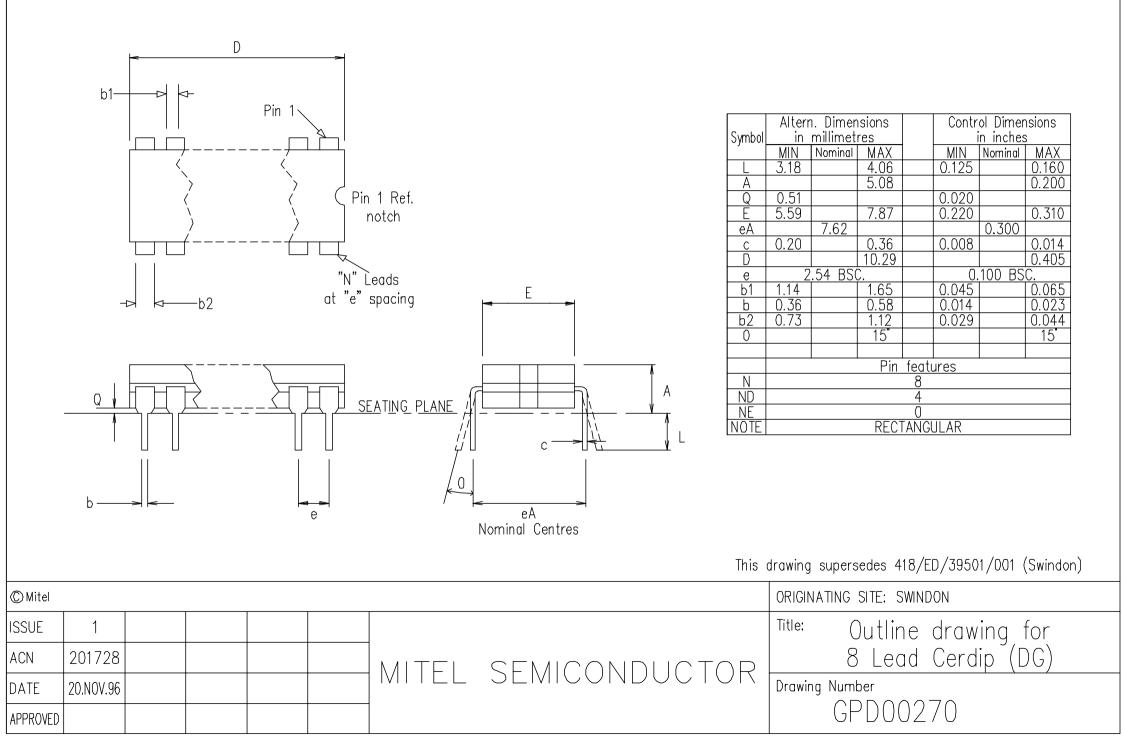
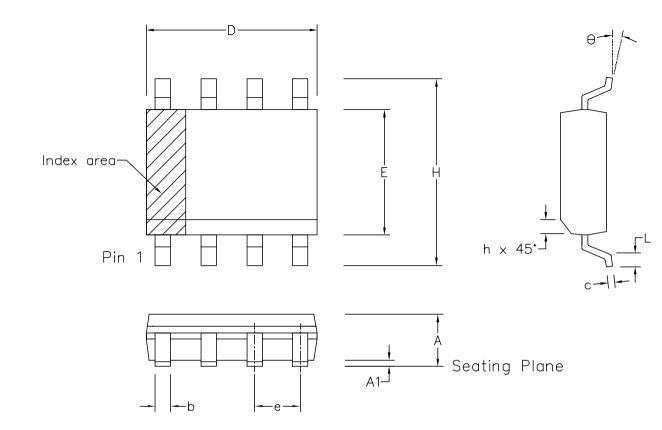


Figure 6 Typical input impedance. Test conditions: supply voltage =5V, ambient temperature =25°C, frequencies in MHz, impedances normalised to  $50\Omega$ 





	Min	Max	Min	Max	
	mm	mm	inch	inch	
A	1.35	1.75	0.053	0.069	
A1	0.10	0.25	0.004	0.010	
D	4.80	5.00	0.189	0.197	
Н	5.80	6.20	0.228	0.244	
E	3.80	4.00	0.150	0.157	
L	0.40	1.27	0.016	0.050	
е	1.27	BSC	0.050_BSC		
b	0.33	0.51	0.013	0.020	
С	0.19	0.25	0.008	0.010	
0	٥	8°	0°	8°	
			0 04 0		
<u>h</u>	0.25	0.50	0.010	0.020	
h	0.25		<u>0.010</u> eatures	0.020	
h N			atures	3	

# Notes:

- 1. The chamfer on the body is optional. If it not present, a visual index feature, e.g. a dot, must be located within the cross-hatched area.
- 2. Controlling dimension are in inches.
- Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
   Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
   Dimension b does not include dambar protusion/intrusion. Allowable dambar protusion shall be 0.004"
- total in excess of b dimension.

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ISSUE	1	2	3	4			Title: Package Outline Drawing for 8 Ids SOIC(N)-0.150" Body Width (MP)
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DATE	5APR95	27FEB97	12JUN97	9DEC97		SLIVICONDUCION	Drawing Number
APPROVED							GPD00010



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